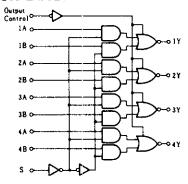
This multiplexer features three-state outputs that can interface directly with and drive data lines of bus-organized systems. With all but one of the common outputs disabled (at a high-impedance state) the low impedance of the single enabled output will drive the bus line to a high or low logic level.

To minimize the possibility that two outputs will attempt to take a common bus to opposite logic levels, the output-enable circuitry is designed such that the output disable times are shorter than the output enable times.

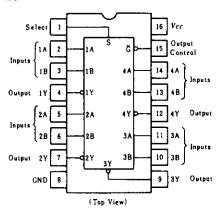
■BLOCK DIAGRAM



RECOMMENDED OPERATING CONDITIONS

Item	Symbol	min	typ	max	Unit		
Output	Іон	_	_	-2.6	mA		
current	lou			8	mA		

PIN ARRANGEMENT



FUNCTION TABLE

_	Input					
oc	S	A	В	Y		
H	Х	Х	Х	Z		
L	L	L	X	Н		
L	L	Н	Х	L		
L	Н	X	L	Н		
L	н	Х	Н	L		

Note) H; high level, L; low level, X; irrelevant Z; off (high-impedance) state of a 3-state output

ELECTRICAL CHARACTERISTICS $(Ta=-20\sim+75^{\circ})$

	Item	Symbol	Test Conditions		min	typ*	max	Unit
Input voltage		VIH			2.0	_	_	V
		V_{tt}				_	0.8	V
Output voltage		Von	$V_{CC} = 4.75 \text{V}, V_{IR} = 2 \text{V}, V_{IL} = 0.8 \text{V},$	Iон = -2.6 mA	2.4	_		v
		17.	$V_{CC} = 4.75 \text{V}, V_{IH} = 2 \text{V}, V_{IL} = 0.8 \text{V}$	IoL -4mA	_		0.4	V
		Vol		IoL =8mA	_		0.5	v
Output current		Іогн	$V_{\rm cc} = 5.25 \text{V}, \ V_{\rm IH} = 2 \text{V}, \ V_{\rm o} = 2.4 \text{V}$		_	_	20	μA
		Iozi	$V_{CC} = 5.25 \text{V}, V_{IR} = 2 \text{V}, V_O = 0.4 \text{V}$		_	_	-20	μA
	S	,	Vcc - 5.25V, V ₁ - 2.7V				40	μA
	except S	Іін			_	_	20	μΑ
Input current	S		Vcc -5.25V, V1-0.4V				-0.8	mA
	except S	In			_		-0.4	mA
	S		Vcc -5.25V, V1-7V				0.2	mA
	except S	It.			_		0.1	mА
Short-circuit output current		Ios	V _{cc} = 5.25V		-30	_	130	mA
Supply current	All outputs high		Vcc -5.25V			_	7	mA
	All outputs low	1cc					11	mA
	All outputs off	1		Ī			12	mA
Input clamp voltage Vik		VIR	$V_{cc} = 4.75 \text{V}, I_{IN} = -18 \text{mA}$				-1.5	V

^{*} VCC=5V, Ta=25°C

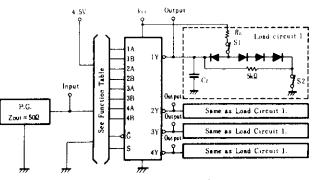
^{**} ICC is measured with all outputs open and all possible inputs grounded while achieving the stated output conditions.

ESWITCHING CHARACTERISTICS ($V_{cc}=5V$, $T_a=25^{\circ}C$)

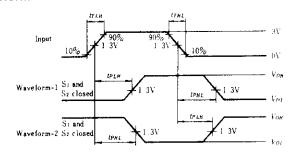
Item	Symbol	Input	Output	Test Conditions	min	typ	max	Unit
Propagation delay time	t PLH	- A, B Y			T -	12	18	ns
	t en.				12	18	ns	
	t PEH			$R_1 = 2 k\Omega$	-	14	21	ns
	t pui.	S	Y	$C_I = 15 \mathrm{pF}$		14	21	ns
Output enable time	t zn	OUTPUT	Y			20	30	ns
	t zı.	CONTROL			_	20	30	ns
Output disable time	t HZ	OUTPUT	v	$R_I = 2 k\Omega$	_	18	30	ns
	tız	CONTROL	Υ	$C_L = 5 pF$	i -	16	25	ns

TESTING METHOD

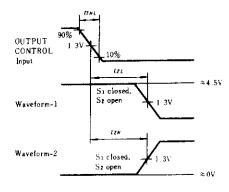
1) Test Circuit

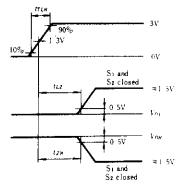


Waveform



- Notes) 1. C_L includes probe and jig capacitance.
 - 2. All diodes are 1S2074 (H).

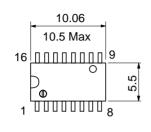


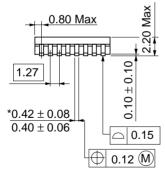


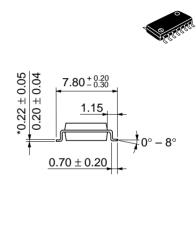
- Notes) 1. Input pulse: $t_{TLH} \le 15 \text{ns}$, $t_{THL} \le 6 \text{ns}$, PRR = 1 MHz,
 - Waveform-1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 - Waveform-2 is for an output with internal conditions such that the output is high except when disabled by the output control.

Unit: mm 19.20 20.00 Max 16 7.40 Max 6.30 1.3 1.11 Max 7.62 5.06 Max 2.54 Min 0.51 Min $0.25^{+0.13}_{-0.05}$ 0.48 ± 0.10 2.54 ± 0.25 $0^{\circ} - 15^{\circ}$ Hitachi Code DP-16 **JEDEC** Conforms EIAJ Conforms Weight (reference value) 1.07 g

Unit: mm



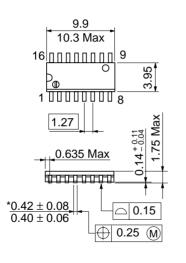


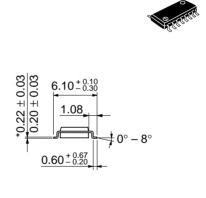


*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DA
JEDEC	_
EIAJ	Conforms
Weight (reference value)	0.24 g

Unit: mm





*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.15 g

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